

# LIGO Laboratory / LIGO Scientific Collaboration

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# ADVANCED LIGO

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# Preparation of an end or input test mass (ETM/ITM) (Hydroxide-Catalysis Bonding of ears)

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#### 1 Introduction

#### 1.1 Purpose and Scope

This document defines the procedure for preparing an ETM/ITM test mass (D080658-v3 and D080657-v3) for installation into the quadruple suspension structure. The procedure consists of hydroxide catalysis bonding on a fused silica 'ear' (suspension element according to D080751-v1) to each of the surfaces S3 and S4 in a well-defined location and re-storing the mass. General hydroxide-catalysis bonding procedures are detailed in E050228. The procedure assumes the mirror substrate has been fully prepared with HR and AR coatings applied to respectively the front and the back surface of the substrate. It includes mirror handling with the ergo-arm during these procedures. Mirror handling procedures with the ergo-arm are detailed in T1000082.

It assumes that the mass has been stored in a COC ETM storage container or 'cake-tin' (D0902146). Both coated surfaces have First Contact films already applied to them. The procedure starts from the point of removing the mass from the 'cake-tin' using the ergo arm. It finishes with the 4-week curing period needed to cure the ears. The test mass is stored back into the cake-tin container during this curing period.

The procedure does not include (at this point) any necessary cleaning and/or baking procedure required prior to inserting the mass into the structure.

The document starts with giving an overview of the required lab-settings and tooling followed by giving the relevant documentation.

It then discusses the detailed steps of the procedure including location, timing, number of personnel needed and tooling needed.

#### 1.2 Required lab-settings

The surfaces must be free of particles, thus, the bonding must take place under a Class 100 laminar flow bench or in a Class 100 clean-room.

Operator must be dressed in clean room attire: overall, boots, head cover, facemask, and approved cleanroom gloves are required.

This clean-room has a sink with running DI water with a resistance of 18 MOhm. It also has two tables of normal height (between 70 and 75 cm).

#### 1.3 Equipment and Materials

- Filtered dry nitrogen
- (De-)Ionizing gun
- High intensity light source (ideally handheld battery supported)
- DI water 18 M $\Omega$  resistance
- Mini centrifuge capacity 6x 1.5 ml (VWR Cat. No. 20668-212)
- Pipettor with tip ejector variable volume,  $2-20 \mu l$ , Eppendorf 2000 (VWR Cat. No. 53511-588)

- Microcentrifuge tubes Eppendorf, 1.5 ml (VWR Cat. No. 20901-551)
- VWR® MiniFuge Microcentrifuge 120V, 50/60Hz (VWR Cat. No. 93000-196)
- Microcentrifuge tubes storing rack (VWR Catalog No. 20901-675)
- Centrifuge tubes polypropylene, graduated, 50 ml (VWR Cat. No. 21008-240)
- Centrifuge tube's rack (VWR cat. No. 21008-485)
- Medical Filter: Whatman Filter Uniprep 0.2UM PK50 UN113ENYL Filter
- Eppendorf\* epTIPS\* Pipet Tips Sterile PCR Clean Filter Tips, 2-20 μl, 10 Racks of 96 Tips (VWR Cat. No. 47745-092)
- Alpha 10 wipes case (VWR Cat. No. TWTX1010)
- Gloves VWR Certi-Clean Class 100 Latex Gloves or Accu Tech Ultra Clean 91300 Gloves.
- Methanol Reagent grade
- Sodium bicarbonate
- Cerium oxide polishing compound
- Micro 90® detergent (International Products Corporation)
- Sodium Silicate Solution from Sigma-Aldrich 338443-1L (~10.6% NaOH, ~26.5% SiO by weight)
- Ultrasonic cleaner BRANSON 8510
- V-block D1001685
- Bonding jig D1001592
- Metric slip gauges
- Allen key for #2-56 socket-head capscrews
- Digital calipers with metric setting

#### 1.4 References

| Design documentation 'glass' essentials    |  |  |  |  |
|--|--|--|--|--|
| D080657                                    | ALIGO COC ITM SUBSTRATE                |  |  |  |
| D080658                                    | ALIGO COC ETM SUBSTRATE                |  |  |  |
| D080751                                    | ETM ITM quad production ear            |  |  |  |
| D0902455                                   | ETM bonded assembly                    |  |  |  |
| D0902456                                   | ITM bonded assembly                    |  |  |  |
| Design documentation of the alignment jigs |  |  |  |  |
| D0901592                                   | ASSEMBLY DRAWING – NP-type bonding jig |  |  |  |

| D0901591        | Baseplate – NP-type bonding jig   |  |  |  |  |  |
|-----------------|---|--|--|--|--|--|
| D1000128        | Penultimate mass prism holder   |  |  |  |  |  |
|                 | Measurement reports on 'glass' essentials   |  |  |  |  |  |
| Q10xxyy         | Relevant test mass control measurements   |  |  |  |  |  |
| Q10xxxx         | Relevant ear control measurements of ears   |  |  |  |  |  |
| Back ground doc |   |  |  |  |  |  |
| E050228         | (Specification) Silicate Bonding Procedure  |  |  |  |  |  |
| T1000137        | Drag wiping and first contact   |  |  |  |  |  |
| T0900402        | Enhanced LIGO core optic drag wipe cleaning procedure   |  |  |  |  |  |
| E0900394        | aLIGO Optic Container Shipping Procedure  |  |  |  |  |  |
| E1000079        | Advanced LIGO First Contact procedure for large optics  |  |  |  |  |  |
| T1000114        | ALIGO NP-type: - Report on Ear Bonding at LASTI 27 <sup>th</sup> August – 31 <sup>st</sup> August |  |  |  |  |  |
| T0900447        | Ear fabrication readiness review  |  |  |  |  |  |
| M080134         | ETM/ITM and BS/FM pitch frequencies and d-values  |  |  |  |  |  |
| T1000082        | Ergo-arm users manual   |  |  |  |  |  |
| D0902146        | ASSEMBLY, ETM, COC OPTIC CONTAINER, ADVANCED LIGO   |  |  |  |  |  |
| E1000079        | First Contact Application and Removal Procedure   |  |  |  |  |  |
| F1000006        | Bond quality monitoring form  |  |  |  |  |  |
| E1000265        | Jig-settings calculation sheet  |  |  |  |  |  |

# 1.5 Version history

04/08/10: Requested DCC number for the document.

08/04/10: Release v1 onto DCC.

# 2 Main procedure

# 2.1 Set jig for the relevant side ("S3" or "S4") of the mass

| Step | What   | Where                | Time          | People                          | Tools  |
|------|--|----------------------|---------------|---------------------------------|--|
| 1    | Select the mass, which side (surface "S3" or "S4"), ear and bonding jig that will be used for the bonding. Calculate the required settings for $D_{\text{slider}}$ and $D_{\text{screw1}}$ for the bonding jig using the (E1000256) and copy onto clean-room paper | In office            | 30 min        | 2 (one calculator, one checker) | Quality control<br>documentation of<br>mass, ear and<br>bonding jig. |
| 2    | Set D <sub>screw</sub> on the left side of the jig (side 1 on the assembly drawing) for bonding onto surface "S3" or the right side of the jig (side 2 on the assembly drawing) for bonding onto surface "S4"  | in bonding cleanroom | 5 min         | 1                               | Bonding jig assy, slip gauges of the right thickness                 |
| 3    | Set D <sub>slider</sub> on both sliders of the jig   | in bonding cleanroom | 5 min         | 1                               | Bonding jig assy,<br>calipers, Allen key<br>for #2-56 cap screw      |
|      |  |                      | <b>40</b> min |                                 | -  |

# 2.2 Set-up mass and ear for cleaning

| Step | What   | Where                   | Time   | People | Tools   |
|------|--|-------------------------|--------|--------|---|
| 4    | Take the mass out of its 'cake-tin' and place onto the V-block on the washing table/sink. This is done using the ergo-arm. Follow instructions for cake-tin. The bonding sides are placed vertically to minimize risk of rinsing water over the coated surfaces of the mass and to give easier access. | in bonding<br>cleanroom | 15 min | 2      | Ergo-arm (T1000082), mass in 'cake-tin' with tooling to open,V- block, isopropanol, optical wipes |
| 5    | Take the ear out of its packaging and place in a petridish on an optical cloth   | in bonding cleanroom    | 2 min  | 1      | Ear, petridish, optical wipe  |
| 6    | Change gloves  | in bonding cleanroom    | 1 min  | 2      | Gloves  |

| Step | What  | Where                | Time   | People | Tools   |
|------|---|----------------------|--------|--------|---|
|      |   |                      | 18 min |        |   |
|      |   |                      |        |        |   |
|      | 2.3 Prepare bonding solution  |                      |        |        |   |
| Step | What  | Where                | Time   | People | Tools   |
| 7    | Pour 2 ml of sodium silicate solution and 12 ml of DI water into a 15 ml centrifuge tube, close the lid, and shake thoroughly for 30 seconds (this gives a 1:6 volumetric ratio of sodium silicate solution to DI water)  | in bonding cleanroom | 1 min  | 1      | 15 ml centrifuge tube, sodium silicate solution, DI water |
| 8    | Transfer the solution into 3 1.5 ml centrifuge tubes. Take care you don't   | in bonding           | 1 min  | 1      | Rack for 1.5 ml   |
| o    | hover with any gear above the tubes at any time. Then close lids. Transfer to centrifuge and let them spin for 30 seconds.  | cleanroom            |        |        | centrifuge tubes, 1.5 ml centrifuge tubes, centrifuge     |
| 9    | Open up two of three centrifuge tubes and transfer to the outer shell of a medical filter. Leave a bit in the centrifuge tubes as this bit will contain the larger particles. Also, stay below the stepped edge of the medical filter (this is the maximum amount the filter can effectively filter). Then place the (closed) filter piece into the outer shell and press down until it clicks into the outer shell edge. | in bonding cleanroom | 1 min  | 1      | 0.2 μl medical filter                                     |
| 10   | Transfer the medical filter with solution to the bonding table and change gloves  | in bonding cleanroom | 1 min  | 1      | Gloves  |
|      |   |                      | 4 min  |        |   |
|      | 2.4 Clean the relevant side ("S3" or "S4") of the mass  |                      |        |        |   |
| Step | What  | Where                | Time   | People | Tools   |
| 11   | Make sure the dry nitrogen supply is open and de-ionizing gun can blow a gentle consistent and well controlled flow.  | in bonding cleanroom | 1 min  | 1      | Dry nitrogen  |
|      | Make sure methanol and optical wipes are ready.   |                      |        |        |   |

| Step | What   | Where                   | Time  | People | Tools  |
|------|--|-------------------------|-------|--------|--|
|      | Get the DI water running gently but solidly through the flexible hose  |                         |       |        |  |
|      | Open petridish with bicarbonate of soda. Put that at the back to minimize risk of contaminating with cerium oxide  |                         |       |        |  |
|      | Open petridish with cerium oxide. Put that in front of the bicarbonate of soda.  |                         |       |        |  |
| 12   | Rinse DI water over side "S3" or "S4" of the TM. Rub the surface with a folded wet optical wipe embedded with cerium oxide paste in a random motion with moderate pressure. Make sure the actual bond area is rubbed best but extend the area to about three times the width and height. The cerium oxide paste should start sticking uniformly over the cleaned surface. The surface should become hydrophilic. Typically 30 seconds of rubbing is enough. Rinse again with DI water and rub with a clean optical wipe to get rid of most cerium oxide. | in bonding cleanroom    | 1 min | 2      | DI water, cerium<br>oxide, optical wipes     |
| 13   | Throw away the cerium oxide cloth and rinse fingers thoroughly.  | in bonding cleanroom    | 1 min | 2      |  |
| 14   | Rub side "S3" or "S4" with a folded wet optical wipe embedded with a copious amount of bicarbonate of soda paste with moderate pressure. Work from the inside out to work remainders of cerium oxide from inside out. Typically 30 seconds of rubbing is enough. Make the cleaning area slightly bigger than was done for the cerium oxide. Rinse with water to wash away bicarbonate of soda.   | in bonding cleanroom    | 1 min | 2      | DI water, bicarbonate of soda, optical wipes |
| 15   | Repeat step 14.  | in bonding cleanroom    | 1 min | 2      | DI water, bicarbonate of soda, optical wipes |
| 16   | Rinse the cleaned area with methanol and blow dry gently with de-<br>ionized nitrogen. Once again work from the clean inner area outward and<br>cover a larger area. Wipe away as many water drops that have run along<br>the barrel away with a cloth soaked in methanol.   | in bonding<br>cleanroom | 1 min | 2      | Methanol, dry<br>nitrogen, optical<br>wipes  |

| Step | What  | Where                | Time   | People | Tools   |
|------|---|----------------------|--------|--------|---|
| 17   | Inspect the cleaned surface: it is verified as cleaned when no particles or films are present when viewed without optical aid at a viewing distance of 5"- 6" while the surface is illuminated by a fiber optic light source against a dark background. | in bonding cleanroom | 1 min  | 2      | Fiber optic light<br>source, magnifying<br>glass (optional) |
| 18   | Change gloves   | in bonding cleanroom | 1 min  | 2      | Gloves  |
| 19   | Lift up the test mass using the ergo-arm and wipe carefully and thoroughly with a cloth soaked in methanol underneath the mass, where water ran.  | in bonding cleanroom | 5 min  | 2      | Ergo-arm, methanol, optical wipes                           |
| 20   | Turn the mass 90 °, such that the cleaned side is pointing upward ready for bonding and cover with an optical wipe.   | in bonding cleanroom | 1 min  | 2      | Optical wipes   |
| 21   | Transport the mass on the ergo-arm to the bonding table and put it down onto the V-block for bonding.   | in bonding cleanroom | 5 min  | 2      |   |
|      |   |                      | 19 min |        |   |

# 2.5 Clean ear

| Step | What   | Where                | Time   | People | Tools                                 |
|------|--|----------------------|--------|--------|---------------------------------------|
| 22   | Make sure step 11 is still true  | in bonding cleanroom | 1 min  | 1      | First Contact, clean room wipes       |
| 23   | Take the ear into an optical cloth and rinse with DI water. Embed another optical wipe with cerium oxide and rub the entire ear with moderate pressure. Make sure all edges and corners are covered. Take about 1 minute. Rinse again with DI water to get rid of most cerium oxide. | in bonding cleanroom | 1 min  | 1      | DI water, cerium oxide, optical wipes |
| 24   | Transfer the ear to another optical wipe embedded with cerium oxide and rub the bonding surface in particular. Do this for 30 seconds.   | in bonding cleanroom | 30 sec | 1      | DI water, cerium oxide, optical wipes |

| Step | What   | Where                | Time   | People | Tools  |
|------|--|----------------------|--------|--------|--|
| 25   | Transfer the ear to another clean optical wipe and rub to remove most cerium oxide. Make sure gloved hands are rinsed thoroughly as well.  | in bonding cleanroom | 1 min  | 1      |  |
| 26   | Transfer the ear to an optical wipe embedded with copious amounts of bicarbonate of soda and rub it with moderate pressure for about 1 minute. Rinse.                                | in bonding cleanroom | 1 min  | 1      | DI water, bicarbonate of soda, optical wipes |
| 27   | Transfer the ear to a fresh optical wipe embedded with copious amounts of bicarbonate of soda and rub in particular the bonding surface with moderate pressure for about 30 seconds. | in bonding cleanroom | 30 sec | 1      | DI water, bicarbonate of soda, optical wipes |
| 28   | Thoroughly rinse the ear and gloved hands with DI water while the ear is lying in a hand upside down, ensuring to never touch the bonding surface with the gloves.                   | in bonding cleanroom | 30 sec | 1      |  |
| 29   | Rinse the ear with methanol and cover with an optical wipe.  | in bonding cleanroom | 30 sec | 1      | Methanol, optical wipe                       |
| 30   | Transfer part back to petridish on bonding table lined with a fresh optical wipe   | in bonding cleanroom | 30 sec | 1      | Petridish, optical wipe                      |
| 31   | Clean gloves   | in bonding cleanroom | 30 sec | 1      | Gloves                                       |
|      |  |                      | 7 min  |        |  |

# 2.6 Bonding

| Step | What   | Where                | Time  | People | Tools |
|------|--|----------------------|-------|--------|-------|
| 32   | Set the pipette to 9.6 µl and lock.  |                      | 1 min |        |       |
| 33   | Take the optical wipe off side 1 of the mass. Take a folded optical wipe soaked with methanol and wipe the bonding surface. Blow dry with dry nitrogen from the de-ionizing gun. Use the fibre optic light to thoroughly | in bonding cleanroom | 1 min |        |       |

| Step | What   | Where                   | Time        | People | Tools  |
|------|--|-------------------------|-------------|--------|--|
|      | inspect the surface for small specks from a distance of 5-6". Wipe and/or blow any specks away.  |                         |             |        |  |
| 34   | Wipe down the bonding jig with methanol to remove any dust and place it on the bonding surface by referencing the front surface ("S1") of the mass and lining the sliders up with the fiducials on surface ("S3"). Tighten the spring-loaded screw onto surface "S2".  | in bonding<br>cleanroom | 3 min       | 1      | Optical wipe,<br>methanol  |
| 35   | Pick up the ear and wipe the bonding surface in one stroke with a folded optical wipe soaked with methanol. Gently blow dry with dry nitrogen using the de-ionizing gun. Use the fibre optic light to thoroughly inspect the surface for small specks from a distance of 5-6". Wipe and/or blow any specks away. Lay the ear back down.  | in bonding<br>cleanroom | 1 min       | 2      | Dry nitrogen, de-<br>ionizing gun, high<br>intensity light source,<br>optical wipe soaked<br>in methanol |
| 36   | Put a pipette point onto the pipette and extract the required solution from the medical filter, making sure not to touch the pipette tip to anything except the solution and making sure to close the filter again. Give the surface of the mass one more glance to ensure no more specks have landed and then place the drop of bonding solution down about 3 cm from the left reference edge and 1 cm from the top reference edge of the bonding jig (middle of the ear). Remove the pipette tip and place the pipette back. | in bonding cleanroom    | 1 min       | 2      | Pipette, pipette tips<br>bonding solution  |
| 37   | Pick up the ear. Give the surface of the mass one more glance to ensure no more specks have landed. Place the ear carefully onto the mass, while lining it up with the top-left corner of the bonding jig hole.  | in bonding cleanroom    | 1 min       | 1      | High intensity light source  |
| 38   | Inspect how the bonding solution spreads. It should spread readily over the entire bonding surface. Viewing at a shearing angle of $\sim\!30$ ° one should see coloured fringes. There might also be bubbles visible. These should be moving towards the edges.  | in bonding cleanroom    | 5-10<br>min | 2      | High intensity light source  |
|      | Note down on the inspection sheet all relevant information including the   |                         |             |        |  |

| Step                  | What   | Where | Time   | People | Tools   |
|-----------------------|--|-------|--------|--------|---|
|                       | state of the bond initially (bubbles and fringes). Keep on checking for about 5 to 10 minutes. |       |        |        |   |
|                       |  |       | 18 min |        |   |
|                       | 2.7 Initial curing and inspection  |       |        |        |   |
| Step                  | What   | Where | Time   | People | Tools   |
| 39                    | Inspect the hand every 20 minutes for the first 2 hours and note down an                       |       | 25 min | 0      | Fibre optic light, pen,                           |
| 39                    | Inspect the bond every 30 minutes for the first 2 hours and note down on the inspection sheet  |       | 5 min  | 1      | inspection sheet                                  |
| the inspection sheet. | the hispection sheet.  |       | 25 min | 0      | F1000006  |
|                       |  |       | 5 min  | 1      |   |
|                       |  |       | 25 min | 0      |   |
|                       |  |       | 5 min  | 1      |   |
|                       |  |       | 25 min | 0      |   |
| 40                    | Remove the bonding jig carefully after 2 hours   |       | 10 min | 1      | Fibre optic light, pen, inspection sheet F1000006 |
| 41                    | I  |       | 55 min | 0      | Fibre optic light, pen                            |
| 41                    | Inspect the bond every hour for the following 3 hours.   |       | 5 min  | 1      | inspection sheet                                  |
|                       |  |       | 55 min | 0      | F1000006  |
|                       |  |       | 5 min  | 1      |   |
|                       |  |       | 55 min | 0      |   |
|                       |  |       | 5 min  | 1      |   |
| 42                    | Leave bond to cure for at least 12 hours before starting the other side.                       |       | 7 hrs  |        |   |
|                       |  |       | 12 hrs |        |   |

#### 2.8 Bond the other side

| Step | What  | Where   | Time           | People | Tools                           |
|------|---|---|----------------|--------|---------------------------------|
| 43   | Use the ergo-arm to move the mass back to the sink to allow for starting the bonding procedure for the other side of the mass | in bonding cleanroom                              | 10 min         | 2      | First Contact, clean room wipes |
| 44   | Repeat steps 1 through 38.  | In office/ in bonding cleanroom                   | 1 hr 46<br>min | 1,2    | See above                       |
| 45   | Repeat the curing steps 39 through 42   | In bonding cleanroom                              | 12 hrs         | 0,1    | See above                       |
| 46   | Use the ergo-arm to store the mass back into it's cake-tin and move the cake-tin to mass storage                              | In bonding<br>cleanroom/<br>mass storage<br>place | 30 min         | 2      | Ergo-arm, cake-tin              |

### 2.9 Curing

| Step | What   | Where        | Time    | People | Tools |
|------|--|--------------|---------|--------|-------|
| 47   | Leave the ears to cure in storage for at least 4 weeks before using them | Mass storage | 28 days | 0      |       |
|      | for the monolithic suspension  |              |         |        |       |

# 3 Back-up procedures

# 3.1 To-do when the bond quality is too low within 8 hours after bonding – debonding

Defining too low quality:

If after bonding an ear it becomes obvious that:

- 1. (despite every caution) a particle is trapped in the bond, which is visible by the eye without magnifying aids, causing a clear dark speck with fringes around it.
- 2. an area of more than  $50 \text{ mm}^2$  (area of  $\sim 7 \text{ x}7 \text{ mm}$  or  $\frac{1}{4}$ " x  $\frac{1}{4}$ ") part of the bonding area is not covered by bonding solution. This can be seen by the fact that the area not bonded is reflective in nature, whereas the area bonded is transparent. The total bonding area is approximately  $1185 \text{ mm}^2$ , which means that the area not bonded can be maximally 4.2%. Bond loss measurements performed by Peter Murray (P0900053) were performed with a bond in which approximately the same percentage of bond area was not bonded.
- 3. If there is a number of small bubbles in the bond initially they can make up a slightly larger percentage of the bond area (up to 8% as it is likely that some or most of the bubbles will move to the sides and disappear. It is not necessary to debond immediately in that case.

It will take approximately 50 to 60 seconds for a bond to settle initially in a laboratory at 20 °C (humidity unknown but typically 30-50% in the laboratory) (Reid et al., Phys. Lett. A, 2007). Initial settling means that with minor force applied it will not move. In the first 8 hours after bonding it is possible to break to bond using a combination of rinsing with copious amounts of DI water and applying a moderate amount of manual force (preferably in a rotation around the axis perpendicular to the bond surface, effectively shearing it). For 1 inch bonded discs a 100% de-bonding success rate was achieved using this method up to 13 hours after the bond was made (T1000464). As the ear bonds cover a larger surface area a shorter time period is recommended. The procedure for this is discussed below.

| Step | What  | Where         | Time   | People | Tools                       |
|------|---|---------------|--------|--------|-----------------------------|
| 1    | Observe that the bond quality is unlikely to meet requirements.   | In clean-room | 10 min | 2      | High intensity light source |
| 2    | Carefully remove the bonding jig, by releasing the spring-loaded bolts and lifting it carefully off the surface.                                | In clean-room | 1min   | 1      |                             |
| 3    | Lift up the mass using the ergo-arm, transport to the washing table and rotate the mass 90° back before placing it down onto the V-block on the | In clean-room | 10 min | 2      | Ergo-arm                    |
| 4    | basin. Run copious amounts of DI water along the bonded ear. Apply a moderate amount of manual force in a shearing direction or rotation. This  | In clean-room | 1 min  | 2      | DI water                    |

| Step | What   | Where         | Time                     | People | Tools  |
|------|--|---------------|--------------------------|--------|--|
| 5    | combination should allow the ear to come off the side of the mass within 3 minutes.  Gently place the ear in a beaker with DI water.   | In clean-room | 1 min                    | 1      | Beaker with DI water   |
| 6    | Keep on rinsing both the flat of the mass with copious amounts of water. Then clean the side of the mass again with cerium oxide and bicarbonate of soda as discussed in section 2.4 in the procedure. | In clean-room | 19 min                   | 2      | DI water, cerium<br>oxide, bicarbonate of<br>soda, methanol,<br>optical wipes, dry<br>nitrogen, de-ionizing<br>gun |
| 7    | Clean the ear again as discussed in section 2.5.   | In clean-room | 7 min                    | 2      | DI water, cerium<br>oxide, bicarbonate of<br>soda, methanol,<br>optical wipes                                      |
| 8    | Repeat the remainder of the bonding procedure discussed in sections 2.6 and 2.9.   | In clean-room | 1 hr 46<br>min<br>12 hrs | 2 0    | See above.   |

# 3.2 To-do when the bond quality is too low after a longer time or if debonding through rinsing doesn't work – ultrasonic debonding

In case no abnormalities were observed within the initial period where debonding by rinsing with copious amounts of water is still possible, there is still the possibility of debonding using ultrasonic stimulation in DI water up to (T1000464 and T1000465) 48 hours after the bond has been made. It is extremely unlikely the bond will change significantly for the worse after 12 hours.

| Step | What   | Where         | Time  | People | Tools |
|------|--|---------------|-------|--------|-------|
| 9    | If the bonding jig has not removed yet, remove the bonding jig carefully, by releasing the spring-loaded bolts and lifting it carefully off the surface. | In clean-room | 1 min | 1      |       |

| Step | What  | Where         | Time   | People | Tools  |
|------|---|---------------|--------|--------|--|
| 10   | Set-up the ultrasonic bath. Put blocks in the bottom to ensure the ear will be submerged completely, but the mass will be submerged by 1 cm at the most. Fill with DI water. Place the stiff lid onto the bath. Attach handles to the V-block and set-up the V-block on top of the ultrasonic bath lid.             | In clean-room | 15 min | 2      | Ultrasonic bath with lid, DI water, V-block plus handles                 |
| 11   | Lift up the mass from the bonding table using the ergo-arm, transport to the V-block on ultrasonic bath. Rotate the mass 180° so that the ear to be de-bonded is facing down and place it carefully on the V-block.   | In clean-room | 10 min | 2      | Ergo-arm, V-block,<br>Ultrasonic bath                                    |
| 12   | Carefully lift up the V-block with mass with 2 people while a third person removes the lid. Lower the V-block with mass down into the ultrasonic bath.  | In clean-room | 3 min  | 3      |  |
| 13   | Switch on the ultrasonic bath: temperature setting: 50° C, running the ultrasonic indefinitely until the ear falls off. If the procedure is commenced within 12 hours after bonding, it should take maximally 30 minutes for the ear to come off. Switch off the ultrasonic bath.                                   | In clean-room | 30 min | 1      |  |
| 14   | If possible remove the ear from the bath and deposit in a beaker with DI water.   | In clean-room | 1 min  | 1      | Beaker with DI water   |
| 15   | Use the handles on the V-block to carefully lift the mass out of the bath with two people and a third person places the lid back onto the bath, before the two people put the mass back down onto it.   | In clean-room | 3 min  | 3      | Lid  |
| 16   | Use the ergo arm to lift the mass onto the V-block on the washing table and rotate 90°. Also dry the barrel of the mass.  | In clean-room | 10 min | 2      | Ergo-arm   |
| 17   | Clean the side of the mass again with cerium oxide and bicarbonate of soda as discussed in section 2.4 in the procedure above. It is likely that a more thorough clean with cerium oxide is necessary in particular along the edges of the old bond, because remnants of bonding solution are likely to be visible. | In clean-room | 19 min | 2      | Optical wipes, cerium oxide, bicarbonate of soda, methanol, dry nitrogen |
| 18   | Select a new ear and repeat the bonding procedure from step 1 in section 2.1  | In clean-room | 1 min  | 1      |  |

#### 3.3 Applying/removing First Contact

#### 3.3.1 Applying

| Step | What          | Where | Time    | People | Tools         |
|------|---------------|-------|---------|--------|---------------|
| 1    | See T1000137. |       | 3 hours | 1      | See T1000137. |

#### 3.3.2 Removing

| Step | What          | Where | Time    | People | Tools         |
|------|---------------|-------|---------|--------|---------------|
| 1    | See T1000137. |       | 3 hours | 1      | See T1000137. |

### 3.4 Drag-wiping

| Step | What          | Where | Time    | People | Tools         |
|------|---------------|-------|---------|--------|---------------|
| 1    | See T1000137. |       | 3 hours | 1      | See T1000137. |

#### 4 Remarks

The old bonding procedure document E050228 uses a 1:4 ratio between sodium silicate solution and water in stead of 1:6. This has been changed by the findings of Elliffe et al and confirmed by ourselves in recent tests as the average strength of 1:6 bonds is somewhat higher and the standard deviation of the strength is lower.

The old procedure doesn't use a centrifuge to get rid of large particles. We do.

The old procedure does use pipetting to take solution out of the bottle. We do not normally use this technique. We normally pour the solution into the 15 ml centrifuge tube.